Room 605, Building 4, 1970 Science Park, Minzhi Community, Minzhi Street, Longhua District, Shenzhen

# 产品规格承认书

## **SPECIFICATIONS**

客户:	
CUSTOMER:	
产品名称:	
DESCRIPTION:	<u>Chip Antenna</u>
客户型号:	
CUSTOMER PART	NO:
产品型号:	
OUR MODEL NO:	PBX1608MC01
日期:	
DATE:	

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UNLESS OTHER SPECIFIED TOLERANCES ON: $X=\pm$ $X.XX=\pm$ $X.XX=\pm$ $X.XX=\pm$ Shenzhen Pengbian Independent of the second of the secon		dustrial		
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DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USE THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS		
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.
TITLE: CHIP2450-1606 Specification		NO.	1000	P1

#### **PBX1608MC01 Specification**

#### 1. Features:

- Stable and reliable in performances
- Low profile, compact size
- RoHS compliance
- SMT processes compatible

#### 2. APPLICATIONS:

- ISM 2 . 4 GHz applications
- ZigBee/BLE applications
- Bluetooth earphone systems
- Hand-held devices when WiFi/Bluetooth functions are needed, e.g., Smart phones
- IEEE802.11 b/g/n
- Wireless PCMCIA cards or USB dongles

#### 3. Part Number Information

AN 1608 S 24 LS A B C D E

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## 4. Product dimensions:

Figure	Symbol	Dimension (mm)
L	L (长)	1.5 ± 0.10
	W (宽)	0.8 ± 0.10
W	T(厚度)	0.50 ± 0.10
A	A (电极宽度)	0.2 ± 0.10

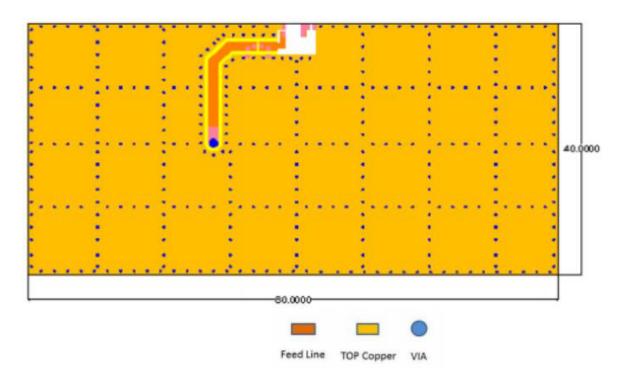
## 5. Electrical Specification:

Specification			
Part Number	AN1608S24LS		
Central Frequency	2450	MHz	
Bandwidth	120 (Min.)	MHz	
Return Loss	-6.5 (Max)	dB	
Peak Gain	1.66	dBi	
Impedance	50	Ohm	
Operating Temperature	-40 <sup>~</sup> +85	C	
Maximum Power	4	W	
Resistance to Soldering Heats	10 ( @ 260 <sup>C</sup> )	sec.	
Polarization	Linear		
Azimuth Beamwidth	Omni-directiona	I	
Termination	Ni / Sn (Leadless	)	

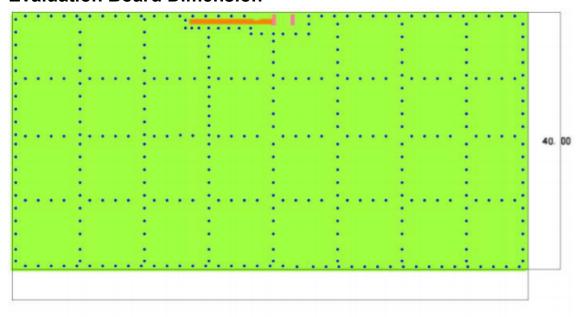
Remark: Bandwidth & Peak Gain was measured under evaluation board of next page

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TITLE: CHIF 2430-1000 Specification	NO.	1000	P1

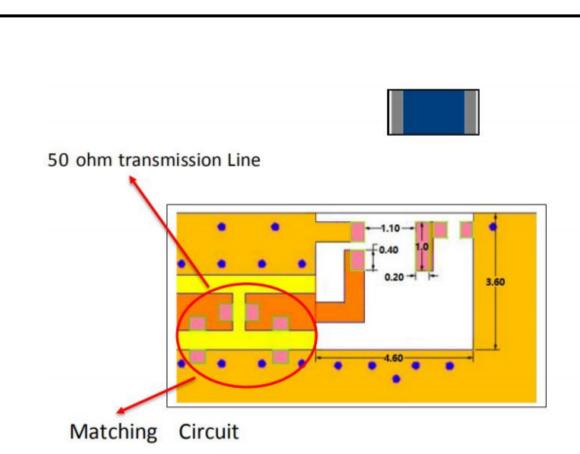
## 6. 1608 PCB



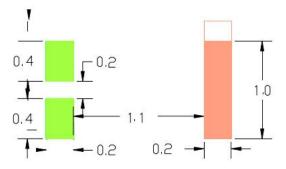
## **2<sup>nd</sup> Evaluation Board Dimension**



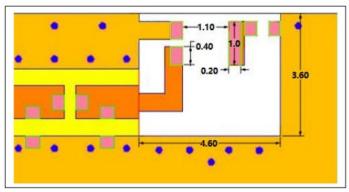
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111EE: 0111F2430-1000 3	TITLE: CHIP2450-1608 Specification		1008	P1



FootPrint (Unit:mm)



#### 2 Layout Dimensions in Clearance area(Size=8.0\*3.0mm)

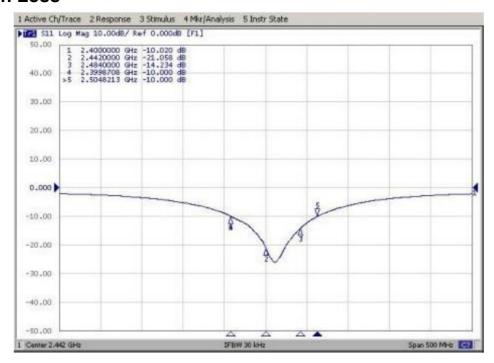




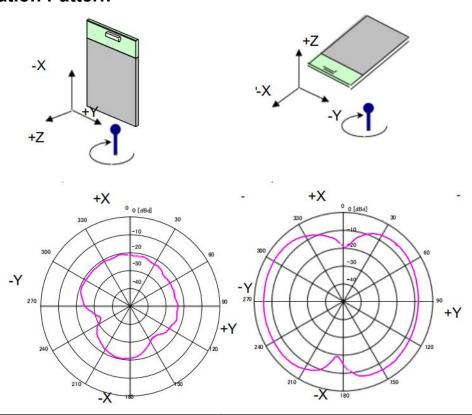
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#### 7. Measurement Results

#### **Return Loss**



#### 7.2 Radiation Pattern

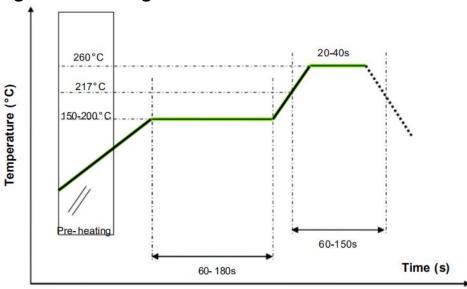


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## 8. Raliability and Test Condictions

Test item	Test condition / Test method	Specification		
JIS C 0050-4.6 *Immersion time : 2 ± 0.5 sec		IIS C 0050-4.6 *Immersion time : 2 ± 0.5 sec		At least 95% of a surface of each terminal electrode must be covered by fresh solder.
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.		
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5± 1 sec.  Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~85°C.		
Resistance to soldering heat  JIS C 0050-5.4	*Preheating temperature: 120~150C,  1 minute.  *Solder temperature: 270±5°C  *Immersion time: 10± 1 sec  Solder: Sn3Ag0.5Cu for lead-free  Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage.  Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.  Loss of metallization on the edges of each electrode shall not exceed 25%.		

## 9. Soldering and Mounting



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#### 11. Storage and Transportation Information

#### **Storage Conditions**

To maintain the solderability of terminal electrodes:

- 1. Temperature and humidity conditions: 10~ 400 and 30~70% RH.
- 2. Recommended products should be used within 6 months from the time of delivery.
- 3. The packaging material should be kept where no chlorine or sulfur exists in the air.

#### **Transportation Conditions**

- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- Bulk handling should ensure that abrasion and mechanical shock are minimized.

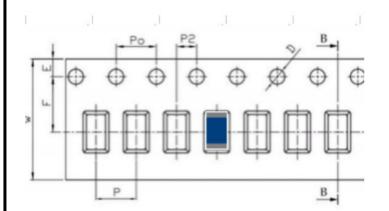
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#### 12. Packing

(1) Quantity/Reel: 5000 pcs/Reel

(2) Plastic tape:

a. Tape Drawing

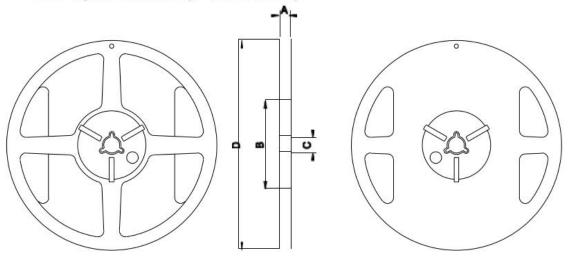


b. Tape Dimensions (unit: mm)

Feature	Specifications	Tolerances	
W	8 00	±0 30	
Р	4.00	±0.10	
E	1.75	±0.10	
F	3 50	±0 10	
P2	2.00	±0.10	
D	1.50	+0. 10	
	1.50	-0.00	
Po	4.00	±0.10	
10Po 40 00		±0 20	

#### c. Reel Drawing

### Reel Specification: (7", Ф180 mm)



7" x 8 mm

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